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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Keith E. FOGEL et al. CONFIRM. NO.: 6557
SERIAL NO.: 10/815,103 ART UNIT: 2826
FILED: 03/31/2004 EXAMINER: L. ANDUJAR
TITLE: INTERCONNECTIONS FOR FLIP-CHIP USING LEAD-FREE
SOLDERS AND HAVING REACTION BARRIER LAYERS

ATTORNEY DOCKET NO.: YOR920030190US1

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
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RESPONSE TO SECOND RESTRICTION REQUIREMENT

In response to the Office Action of July 11, 2006, Applicants elect claims directed to the method of forming a three layer BLM. However, the Office Action is incorrect in that this is the species of Fig. 1 (not Fig. 4). The layer 38 in both Fig. 1 and Fig. 4 is optional.

Claims 15, 16, and 29 are generic. Claims 17-27 and 30-36 clearly read on the elected method of forming the species of Fig. 1. It is believed that claims 37-43 are closer in kind to the elected claims than the non-elected, and should also be examined.

Respectfully submitted,

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August 11, 2006
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